

IN THE CLAIMS:

Kindly cancel claims 1-12 without prejudice or disclaimer recited thereof.

Kindly add the following new claims:

13.(NEW) A component mounting method comprising:

carrying a circuit board to a component mounting position;

sucking up a component by a suction nozzle of a head;

moving the component sucked to the nozzle of the head to the mounting position;

mounting the component to a specified site of the circuit board;

after the mounting, transferring a circuit board with respect to the component mounting position;

moving the head to above a component discarding box during the transferring of the circuit board;

feeding compressed air to one of suction nozzles of the head so as to remove a component remained at the suction nozzle due to vacuum residual pressure while dust and the like material that is sticking to the suction nozzle is removed away simultaneously.

14.(NEW) A component mounting method defined in claim 13, wherein when the circuit board is transferred with respect to the component mounting position during the moving of the head to above a component discarding box, one of circuit boards is carried into the component mounting position and/or the circuit board is carried out after the component-mounting operation.
